Embedded MXM Modules
NVIDIA Blackwell Architecture

Mobile PCI Express Modules with NVIDIA Embedded GPUs

NVIDIA RTX PRO



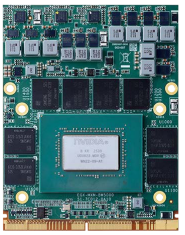
• EGX-MXM-BW500



• EGX-MXM-BW2000



• EGX-MXM-BW4000



• EGX-MXM-BW5000

Features

- NVIDIA Blackwell architecture
- Standard MXM 3.1 Type A/B form factor
- PCIe Gen 5 up to x16 interface
- Up to 10,496 CUDA® Cores, 80 RT Cores, and 328 Tensor Cores
- Up to 49.8 TFLOPS peak FP32 performance
- Up to 24GB GDDR7 memory, 256-bit
- Up to 896GB/s memory bandwidth
- Support up to 4xDP 1.4a displays, 150W TGP
- 5-year Availability

Ordering Information

EGX-MXM-BW500	Embedded NVIDIA RTX PRO 500 Blackwell, MXM 3.1 Type A, 82 x 70mm, PCIe Gen5 x8
EGX-MXM-BW2000	Embedded NVIDIA RTX PRO 2000 Blackwell, MXM 3.1 Type A, 82 x 70mm, PCIe Gen5 x8
EGX-MXM-BW4000	Embedded NVIDIA RTX PRO 4000 Blackwell, MXM 3.1 Type B, 82 x 105mm, PCIe Gen5 x16
EGX-MXM-BW5000	Embedded NVIDIA RTX PRO 5000 Blackwell, MXM 3.1 Type B, 82 x 105mm, PCIe Gen5 x16

Optional Accessories

Thermal Solutions

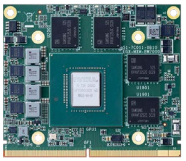
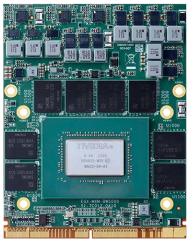
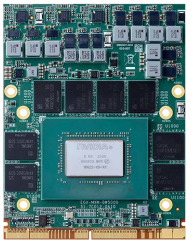
THSF-MXMA-BW	Blackwell Type A active thermal solution (active cooler)
THSF-MXMB-BW	Blackwell Type B active thermal solution (active cooler)
THSP-MXMA-BW	Blackwell Type A active thermal solution (Heat Spreader)
THSP-MXMB-BW	Blackwell Type B active thermal solution (Heat Spreader)

Interposer Card

EGX-MXM-AD	Embedded Graphics converter, MXM 3.1/3.0 to PCIe

Distribuída no Brasil pela LRI | vendas@lri.com.br | 51 2129-3000

Specifications

Model Name	EGX-MXM-BW500	EGX-MXM-BW2000	EGX-MXM-BW4000	EGX-MXM-BW5000
Graphic Core				
Graphic Architecture	NVIDIA® RTX PRO™ 500 Blackwell	NVIDIA® RTX PRO™ 2000 Blackwell	NVIDIA® RTX PRO™ 4000 Blackwell	NVIDIA® RTX PRO™ 5000 Blackwell
Memory	6GB GDDR7 memory, 96-bit, Bandwidth: 288GB/s	8GB GDDR7 memory, 128-bit, Bandwidth: 384GB/s	16GB GDDR7 memory 256-bit Bandwidth 896GB/s	24GB GDDR7 memory 256-bit Bandwidth 896GB/s
ECC Support	No	Yes	Yes	Yes
GPGPU Computing				
CUDA® Cores	1,792 CUDA® Cores, 9.2 TFLOPS Peak FP32 Performance	3,328 CUDA® Cores, 17.7 TFLOPS Peak FP32 Performance	7,680 CUDA® Cores 38.7 TFLOPS Peak FP32 Performance	10,496 CUDA® Cores 49.8 TFLOPS Peak FP32 Performance
Tensor Cores	56	104	240	328
RT Cores	14	26	60	80
Compute API	CUDA® Toolkit 8.0 and above, CUDA® Compute version 8 and above, OpenCL™ 1.2			
Graphics API	DirectX® 12.1, OpenGL® 4.6			
Display				
Display Outputs	3x DP 2.1a	3x DP 2.1a	4x DP 2.1a	4x DP 2.1a
	HDMI 2.1, 4K at 120Hz or 8K at 60Hz with 10-bit color depth			
Interface	PCIe Gen4/5 x8	PCIe Gen4/5 x8	PCIe Gen 4/5 x16	PCIe Gen4/5 x16
Mechanicals				
Dimensions	82 (W) x 70 (D) x 4.8 (H) mm		82 (W) x 105 (D) x 4.8 (H) mm	
Form Factor	Standard MXM 3.1 Type A		Standard MXM 3.1 Type B	
Environmental				
Operating Temperature	Standard: 0˚C – 55˚C Extended Temperature: -40˚C – 85˚C*			Standard: 0˚C–45˚C Extended Temperature: -40˚C – 85˚C*
Module Power Consumption	60W Optional: 35W-60W	60W Optional: 45W-100W	115W Optional: 80W-150W	115W Optional: 95W-150W
SW Support				
OS Support	Windows 11, 10 & Linux Drivers, 64-bit			

*For detailed support regarding wide-temperature specifications, please contact your account manager.

NVIDIA Preferred Partner

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